



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## Features

- Superior circuit protection
- Overcurrent and overvoltage protection
- Blocks surges up to rated limits
- High-speed performance
- Small SMT package
- Agency listing: <sup>®</sup>

## Applications

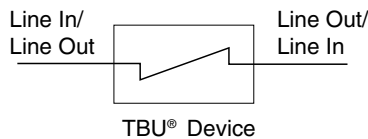
- Voice / VDSL cards
- Protection modules and dongles
- Process control equipment
- Test and measurement equipment
- General electronics

# TBU-CA Series - TBU<sup>®</sup> High-Speed Protectors

### General Information

The TBU-CA Series of Bourns<sup>®</sup> TBU<sup>®</sup> products are low capacitance single bidirectional high-speed protection components, constructed using MOSFET semiconductor technology, and designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.

The TBU<sup>®</sup> high-speed protector placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics will not be exposed to large voltages or currents during surge events. The TBU<sup>®</sup> device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.



### Agency Listing

Description	
UL	File Number: E315805

### Absolute Maximum Ratings (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Value	Unit
V <sub>imp</sub>	Peak impulse voltage withstand with duration less than 10 ms	TBU-CA025-xxx-WH	250	V
		TBU-CA040-xxx-WH	400	
		TBU-CA050-xxx-WH	500	
		TBU-CA065-xxx-WH	650	
		TBU-CA085-xxx-WH	850	
V <sub>rms</sub>	Continuous A.C. RMS voltage	TBU-CA025-xxx-WH	100	V
		TBU-CA040-xxx-WH	200	
		TBU-CA050-xxx-WH	250	
		TBU-CA065-xxx-WH	300	
		TBU-CA085-xxx-WH	425	
T <sub>op</sub>	Operating temperature range		-55 to +125	°C
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
T <sub>jmax</sub>	Maximum Junction Temperature		+125	°C
ESD	HBM ESD protection per IEC 61000-4-2		±2	kV

## **BOURNS<sup>®</sup>**

**Asia-Pacific:** Tel: +886-2 2562-4117 • Fax: +886-2 2562-4116

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[www.bourns.com](http://www.bourns.com)

\*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

# TBU-CA Series - TBU® High-Speed Protectors

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## Electrical Characteristics (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Min.	Typ.	Max.	Unit	
I <sub>trigger</sub>	Current required for the device to go from operating state to protected state	TBU-CAxxx-050-WH	50	75	100	mA	
		TBU-CAxxx-100-WH	100	150	200		
		TBU-CAxxx-200-WH	200	300	400		
		TBU-CAxxx-300-WH	300	450	600		
		TBU-CAxxx-500-WH	500	750	1000		
R <sub>device</sub>	Series resistance of the TBU device	V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 50 mA	TBU-CA025-050-WH		13.3	15.3	Ω
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 100 mA	TBU-CA025-100-WH		7.1	8.2	
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 200 mA	TBU-CA025-200-WH		4.2	4.8	
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 300 mA	TBU-CA025-300-WH		3.2	3.8	
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 500 mA	TBU-CA025-500-WH		2.6	3.0	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 50 mA	TBU-CA040-050-WH		14.3	16.5	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 100 mA	TBU-CA040-100-WH		8.1	9.4	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 200 mA	TBU-CA040-200-WH		5.2	6.0	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 300 mA	TBU-CA040-300-WH		4.3	5.0	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 500 mA	TBU-CA040-500-WH		3.6	4.2	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 50 mA	TBU-CA050-050-WH		15.7	18.0	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 100 mA	TBU-CA050-100-WH		9.5	10.9	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 200 mA	TBU-CA050-200-WH		6.6	7.5	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 300 mA	TBU-CA050-300-WH		5.6	6.5	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 500 mA	TBU-CA050-500-WH		5.0	5.7	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 50 mA	TBU-CA065-050-WH		17.7	20.3	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 100 mA	TBU-CA065-100-WH		11.5	13.2	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 200 mA	TBU-CA065-200-WH		8.6	9.8	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 300 mA	TBU-CA065-300-WH		7.6	8.8	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 500 mA	TBU-CA065-500-WH		7.0	8.0	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 50 mA	TBU-CA085-050-WH		21.4	24.5	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 100 mA	TBU-CA085-100-WH		15.2	17.4	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 200 mA	TBU-CA085-200-WH		12.3	14.0	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 300 mA	TBU-CA085-300-WH		11.3	13.0	
V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 500 mA	TBU-CA085-500-WH		10.7	12.2			
t <sub>block</sub>	Time for the device to go from normal operating state to protected state				1	μs	
I <sub>Q</sub>	Current through the triggered TBU® device with 50 Vdc circuit voltage		0.25	0.50	1.00	mA	
V <sub>reset</sub>	Voltage below which the triggered TBU® device will transition to normal operating state		12	16	20	V	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using recommended pad layout			98		°C/W	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using heat sink on board (6 cm <sup>2</sup> ) (1 in <sup>2</sup> )			40		°C/W	

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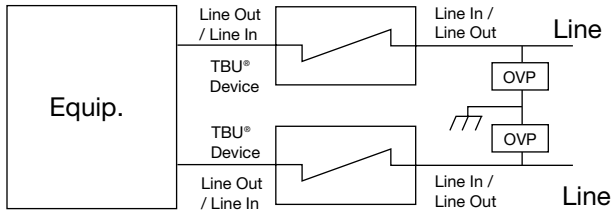
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# TBU-CA Series - TBU® High-Speed Protectors

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## Reference Application

The TBU® devices are general use protectors used in a wide variety of applications. The maximum voltage rating of the TBU® device should never be exceeded. Where necessary, an OVP should be employed to limit the maximum voltage. A cost-effective protection solution combines Bourns® TBU® protection devices with a pair of Bourns® MOVs. For bandwidth sensitive applications, a Bourns® GDT may be substituted for the MOV.



## Basic TBU Operation

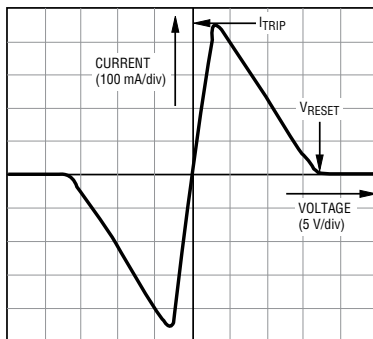
The TBU® device, constructed using MOSFET semiconductor technology, placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events. The TBU® device operates in approximately 1  $\mu$ s - once line current exceeds the TBU® device's trigger current  $I_{trigger}$ . When operated, the TBU® device will limit the current to less than the  $I_{trigger}$  value within the  $t_{block}$  duration. If voltage above  $V_{reset}$  is continuously sustained, the TBU® device will subsequently reduce the current to a quiescent current level within a period of time that is dependent upon the applied voltage.

After the surge, the TBU® device resets when the voltage across the TBU® device falls to the  $V_{reset}$  level. The TBU® device will automatically reset on lines which have no DC bias or have DC bias below  $V_{reset}$  (such as unpowered signal lines).

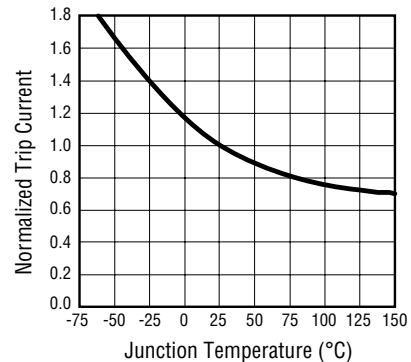
If the line has a normal DC bias above  $V_{reset}$ , the voltage across the TBU® device may not fall below  $V_{reset}$  after the surge. In such cases, special care needs to be taken to ensure that the TBU® device will reset, with software monitoring as one method used to accomplish this. Bourns application engineers can provide further assistance.

## Performance Graphs

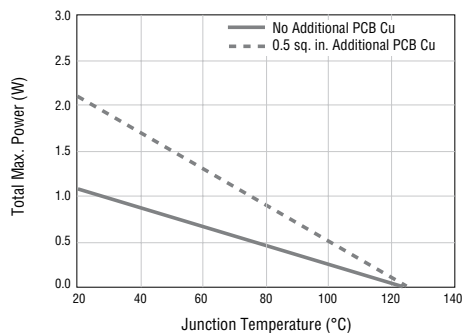
### Typical V-I Characteristics (TBU-CA050-300-WH)



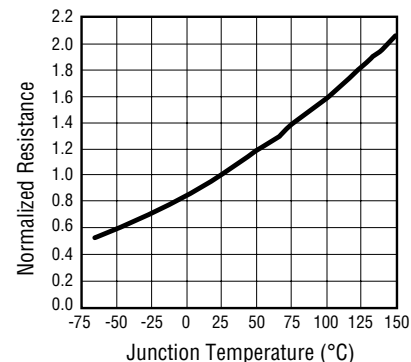
### Typical Trigger Current vs. Temperature



### Power Derating Curve



### Typical Resistance vs. Temperature



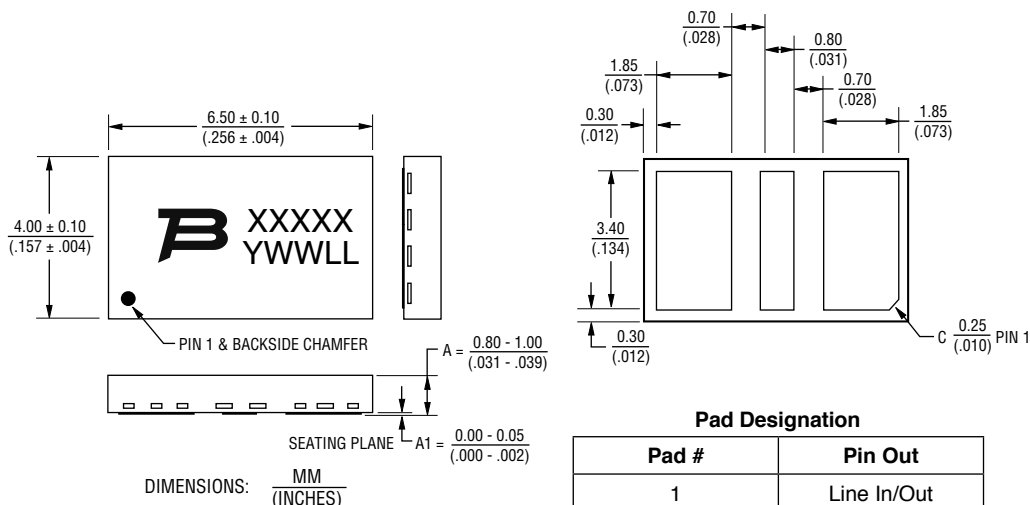
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# TBU-CA Series - TBU® High-Speed Protectors

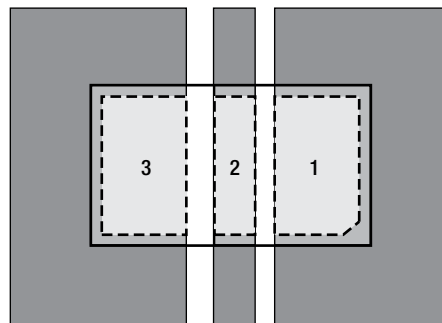
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## Product Dimensions



## Recommended Pad Layout

TBU® High-Speed Protectors have a 100 % matte-tin termination finish. For improved thermal dissipation, the recommended layout uses PCB copper areas which extend beyond the exposed solder pad. The exposed solder pads should be defined by a solder mask which matches the pad layout of the TBU® device in size and spacing. It is recommended that they should be the same dimension as the TBU® pads but if smaller solder pads are used, they should be centered on the TBU® package terminal pads and not more than 0.10-0.12 mm (0.004-0.005 in.) smaller in overall width or length. Solder pad areas should not be larger than the TBU® pad sizes to ensure adequate clearance is maintained. The recommended stencil thickness is 0.10-0.12 mm (0.004-0.005 in.) with a stencil opening size 0.025 mm (0.0010 in.) less than the solder pad size. Extended copper areas beyond the solder pad significantly improve the junction to ambient thermal resistance, resulting in operation at lower junction temperatures with a corresponding benefit of reliability. All pads should soldered to the PCB, including pads marked as NC or NU but no electrical connection should be made to these pads. For minimum parasitic capacitance, it is recommended that signal, ground or power signals are not routed beneath any pad.



Dark grey areas show added PCB copper area for better thermal resistance.

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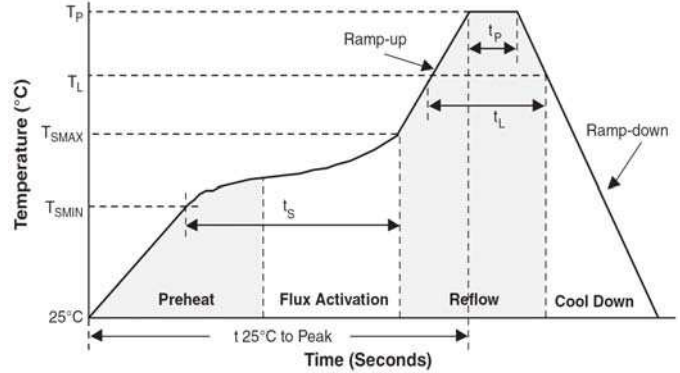
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# TBU-CA Series - TBU® High-Speed Protectors

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## Reflow Profile

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C/sec. max.
Preheat <ul style="list-style-type: none"> <li>- Temperature Min. (T<sub>smin</sub>)</li> <li>- Temperature Max. (T<sub>smax</sub>)</li> <li>- Time (t<sub>smin</sub> to t<sub>smax</sub>)</li> </ul>	150 °C 200 °C 60-180 sec.
Time maintained above: <ul style="list-style-type: none"> <li>- Temperature (T<sub>L</sub>)</li> <li>- Time (t<sub>L</sub>)</li> </ul>	217 °C 60-150 sec.
Peak/Classification Temperature (T <sub>p</sub> )	260 °C
Time within 5 °C of Actual Peak Temp. (t <sub>p</sub> )	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.

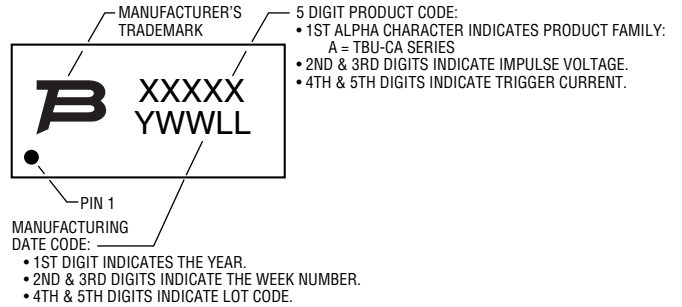


## How to Order

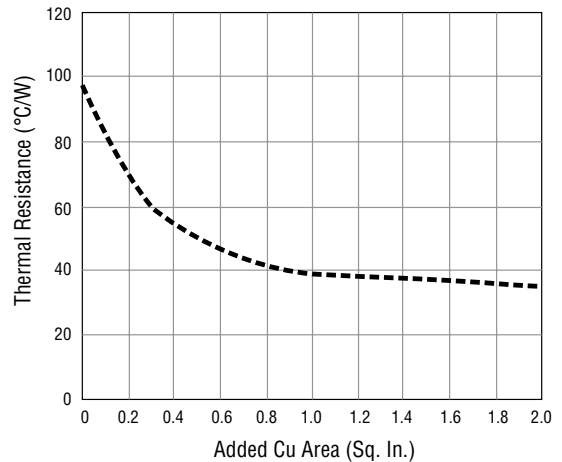
**TBU - CA 085 - 500 - WH**

TBU® Product	_____
Series	_____
CA = Bi-Series	
Impulse Voltage Rating	_____
025 = 250 V	
040 = 400 V	
050 = 500 V	
065 = 650 V	
085 = 850 V	
Trigger Current	_____
050 = 50 mA	
100 = 100 mA	
200 = 200 mA	
300 = 300 mA	
500 = 500 mA	
Hold to Trip Ratio Suffix	_____
W = Hold to Trip Ratio	
Package Suffix	_____
H = DFN Package	

## Typical Part Marking



## Thermal Resistance vs Additional PCB Cu Area



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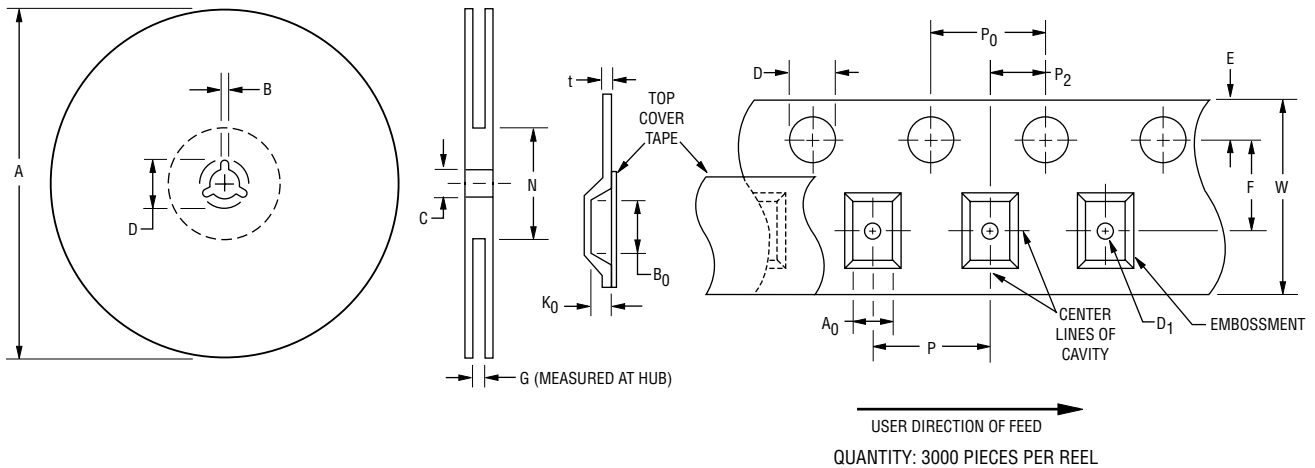
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# TBU-CA Series - TBU® High-Speed Protectors

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## Packaging Specifications



A		B		C		D		G	N
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
326	330	1.5	2.5	12.8	13.5	20.2	-	16.5	102
(12.835)	(13.002)	(.059)	(.098)	(.504)	(.531)	(.795)		(.650)	(4.016)

A <sub>0</sub>		B <sub>0</sub>		D		D <sub>1</sub>		E		F	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.
4.3	4.5	6.7	6.9	1.5	1.6	1.5	-	1.65	1.85	7.4	7.6
(.169)	(.177)	(.264)	(.272)	(.059)	(.063)	(.059)		(.065)	(.073)	(.291)	(.299)
K <sub>0</sub>		P		P <sub>0</sub>		P <sub>2</sub>		t		W	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
1.0	1.2	7.9	8.1	3.9	4.1	1.9	2.1	0.25	0.35	15.7	16.3
(.039)	(.047)	(.311)	(.319)	(.159)	(.161)	(.075)	(.083)	(.010)	(.014)	(.618)	(.642)

DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

REV. 01/17

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